

FIG. 1

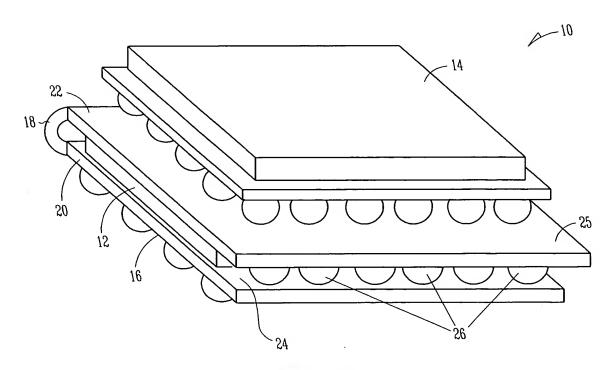
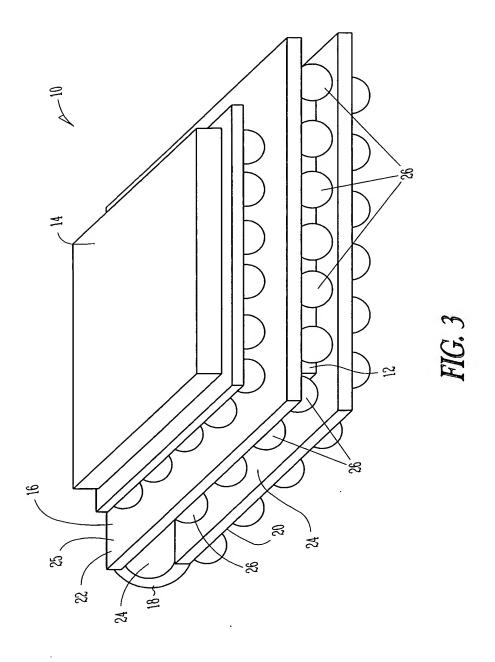
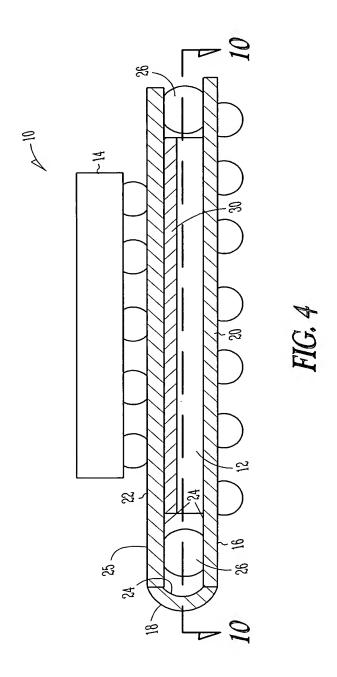


FIG. 2

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TITLE: SEMICONDUCTING DEVICE WITH FOLDED INTERPOSER

INVENTOR'S NAME: IWEN CHAO, ET AL.
SERIAL NO.: 10/812,277 DOCKET NO.: 884.C26US1

REPLACEMENT SHEET

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SECURING A FIRST DIE TO A FIRST SECTION OF AN INTERPOSER, THE INTERPOSER INCLUDING A FIRST CONDUCTOR AND A SECOND CONDUCTOR ON A FIRST SURFACE OF THE INTERPOSER

- SOLDERING THE FIRST DIE TO THE INTERPOSER

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FOLDING THE INTERPOSER TO SECURE THE FIRST DIE TO A SECOND SECTION OF THE INTERPOSER AND TO CONNECT THE FIRST CONDUCTOR TO THE SECOND CONDUCTOR TO FORM A CONTACT

- SOLDFRING THE FIRST CONDUCTOR TO THE SECOND CONDUCTOR
- PLACING AN ADHESIVE ON THE FIRST DIE AND CONNECTING THE SECOND SECTION OF THE INTERPOSER TO THE ADHESIVE
- FORMING A CONTACT ON AN OPPOSING SIDE OF THE FIRST DIE
- CONNECTING EACH OF THE CONDUCTORS TO ANOTHER CONDUCTOR TO FORM A PLURALITY OF CONTACTS THAT EXTEND FROM THE FIRST SURFACE OF THE INTERPOSER BETWEEN THE FIRST SECTION AND THE SECOND SECTION
 - FORMING AT LEAST ONE CONTACT ON AN OPPOSING SIDE OF THE FIRST DIE
 - FORMING AT LEAST ONE CONTACT ON EACH SIDE OF THE FIRST DIE EXCEPT FOR THE ONE SIDE OF THE FIRST DIE
 - FORMING AT LEAST ONE CONTACT ON EACH SIDE OF THE FIRST DIE

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SECURING A SECOND DIE TO A SECOND SURFACE OF THE INTERPOSER SUCH THAT THE FIRST AND SECOND DICE ARE STACKED ONE ON TOP OF ANOTHER AND ELECTRICALLY COUPLED BY THE INTERPOSER AND THE CONTACT

- SOLDERING THE SECOND DIE TO THE SECOND SURFACE OF THE INTERPOSER

REPLACEMENT SHEET 5/7 -8 -9 \approx ₹~ K3 -ಜ-

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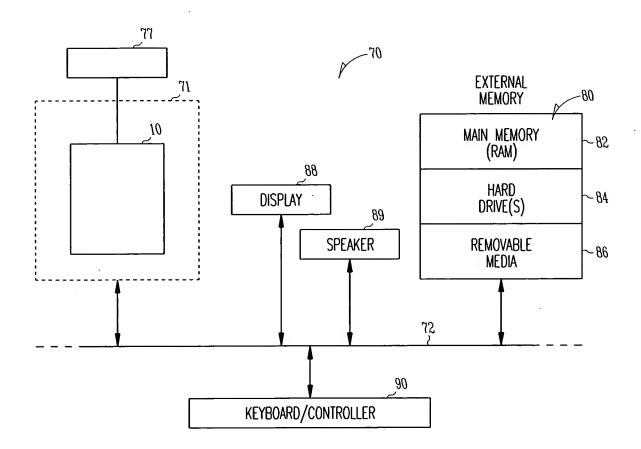


FIG. 8

TITLE: SEMICONDUCTING DEVICE WITH FOLDED INTERPOSER

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NEW SHEET

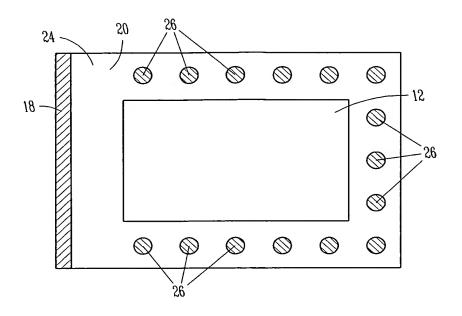


FIG. 9

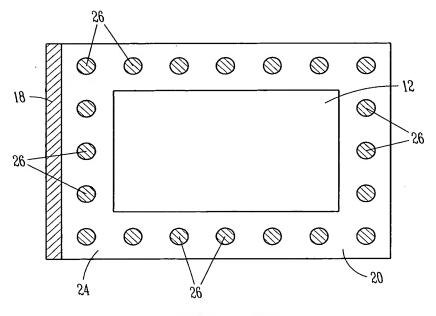


FIG. 10